

WSD30L120DN56

P-Ch MOSFET

General Description

The WSD30L120DN56 is the highest performance trench P-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSD30L120DN56 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Absolute Maximum Ratings

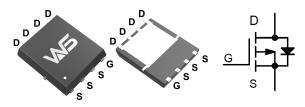
Product Summery

BVDSS	RDSON	ID
-30V	3.6mΩ	-120A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFN5X6-8 Pin Configuration



		Rating		
Symbol	Parameter	10s	Steady State	Units
V _{DS}	Drain-Source Voltage	-:	30	V
V _{GS}	Gate-Source Voltage	±	20	V
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-1	20	А
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ -10V ¹	-7	-76	
I _D @T _A =25℃	Continuous Drain Current, V _{GS} @ -10V ¹	-27	-22	А
I _D @T _A =70℃	Continuous Drain Current, V _{GS} @ -10V ¹	-24	-19	А
I _{DM}	Pulsed Drain Current ² -400		А	
EAS	Single Pulse Avalanche Energy ³	324		mJ
I _{AS}	Avalanche Current	-36		А
P _D @T _C =25℃	Total Power Dissipation ⁴ 78		W	
P _D @T _A =25℃	Total Power Dissipation ⁴	6.8	6.25	W
T _{STG}	Storage Temperature Range	-55 to 150		°C
TJ	Operating Junction Temperature Range	-55 to 150		°C

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
R _{eja}	Thermal Resistance Junction-Ambient ¹		55	°C/W
R _{θJA}	Thermal Resistance Junction-Ambient ¹ (t ≤10s)		20	°C/W
R _{eJC}	Thermal Resistance Junction-Case ¹		1.6	°C/W





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Electrical Characteristics (T_J=25 ^(C), unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$, I_D=-1mA		-0.0232		V/℃
Б	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-30A		2.9	3.6	
R _{DS(ON)}		V _{GS} =-4.5V , I _D =-10A		5.0	6.8	mΩ
V _{GS(th)}	Gate Threshold Voltage		-1.2	-1.5	-2.5	V
$ riangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS} = V_{DS}$, $I_D = -2500A$		4.6		mV/℃
	Drain Source Lookage Current	V_{DS} =-24V , V_{GS} =0V , T _J =25 $^{\circ}$ C			-1	uA
I _{DSS}	Drain-Source Leakage Current	V_{DS} =-24V , V_{GS} =0V , T _J =55 $^\circ$ C			-5	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm20V$, $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-30A		28		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2	5	Ω
Qg	Total Gate Charge (-4.5V)			135		
Q _{gs}	Gate-Source Charge			12		nC
Q _{gd}	Gate-Drain Charge			36		
T _{d(on)}	Turn-On Delay Time			22		
Tr	Rise Time	V_{DD} =-15V , V_{GEN} =-10V , R_{G} =6 Ω		25		
T _{d(off)}	Turn-Off Delay Time	I _D =-1A ,R∟=15Ω		163		ns
T _f	Fall Time			104		
Ciss	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		6100		
C _{oss}	Output Capacitance			1130		pF
C _{rss}	Reverse Transfer Capacitance			1110		1

Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy ⁵	V _{DD} =-25V , L=0.5mH , I _{AS} =-36A	300			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}				-40	А
I _{SM}	Pulsed Source Current ^{2,6}	$-V_{G}=V_{D}=0V$, Force Current			-400	А
V _{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =-1A , T_{J} =25 $^{\circ}$ C			-1	V
t _{rr}	Reverse Recovery Time	I⊧=-15A , dl/dt=100A/µs ,		32		nS
Qrr	Reverse Recovery Charge	T J =25 ℃		16		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.

2.The data tested by pulsed , pulse width $\,\leq\,$ 300us , duty cycle $\,\leq\,$ 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.5mH, I_{AS}=-36A

4.The power dissipation is limited by 150 $^\circ\!\!\mathbb{C}$ junction temperature

5.The Min. value is 100% EAS tested guarantee.

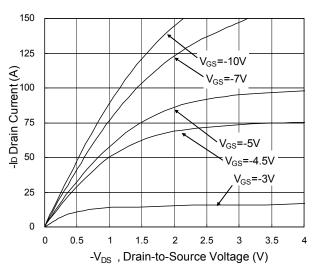
6.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.



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Typical Characteristics





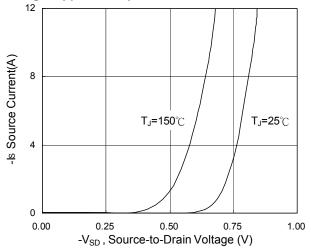
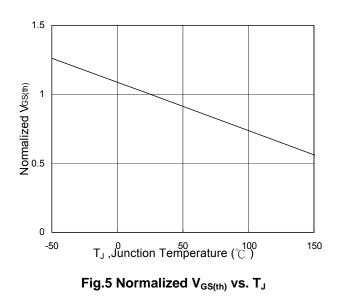


Fig.3 Forward Characteristics of Reverse



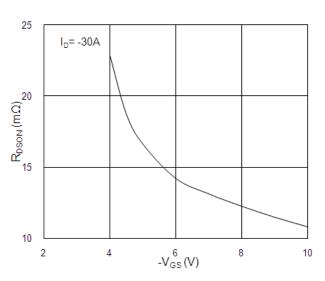


Fig.2 On-Resistance vs. G-S Voltage

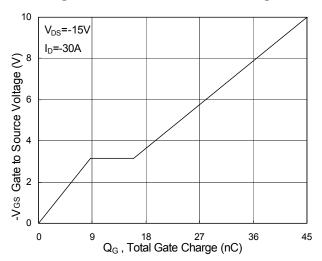


Fig.4 Gate-Charge Characteristics

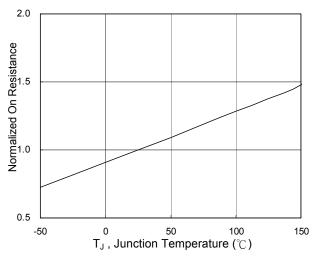


Fig.6 Normalized R_{DSON} vs. T_J

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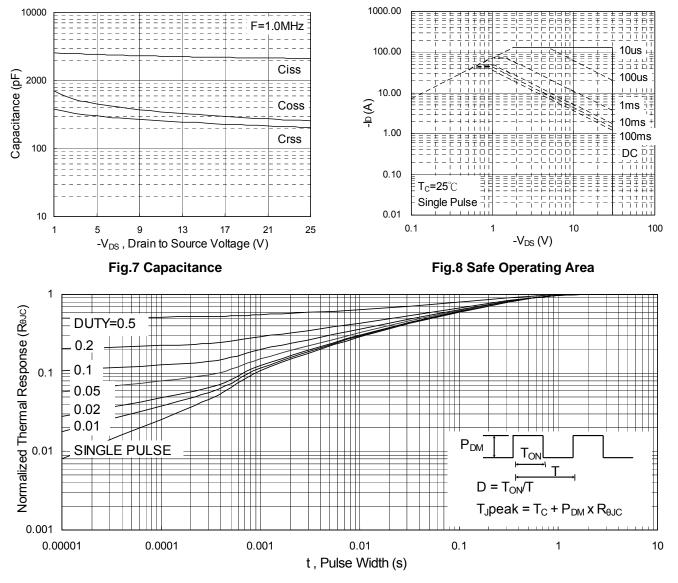
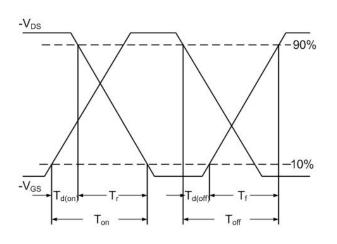


Fig.9 Normalized Maximum Transient Thermal Impedance





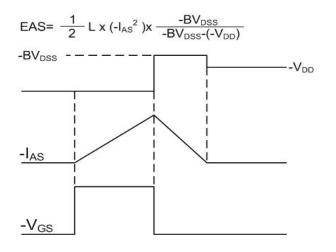


Fig.11 Unclamped Inductive Switching Waveform



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